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Details

Product Status	Active
Applications	Trusted Platform Module (TPM)
Core Processor	16-Bit
Program Memory Type	NVM (6.8kB)
Controller Series	-
RAM Size	-
Interface	SPI
Number of I/O	1
Voltage - Supply	1.65V ~ 3.6V
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	PG-VQFN-32-13
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/slb9670vq20fw760xuma1

Trusted Platform Module

TPM

SLB 9670 TCG Family 2 Level 00 Rev. 01.16

SLB 9670VQ2.0

SLB 9670XQ2.0

Data Sheet

Revision 1.0, 2015-11-05

Chip Card and Security

Revision History

Page or Item	Subjects (major changes since previous revision)
Revision 1.0, 2015-11-05	
	Initial version



Table of Contents

Table of Contents

1	Overview	6
1.1	Power Management	6
2	Device Types / Ordering Information	6
3	Pin Description	7
3.1	Typical Schematic	9
4	Electrical Characteristics	10
4.1	Absolute Maximum Ratings	10
4.2	Functional Operating Range	10
4.3	DC Characteristics	11
4.4	AC Characteristics	12
4.5	Timing	13
5	Package Dimensions (VQFN)	14
5.1	Packing Type	14
5.2	Recommended Footprint	14
5.3	Chip Marking	15



List of Figures

List of Figures

Figure 3-1	Pinout of the SLB 9670VQ2.0 (PG-VQFN-32-13 Package, Top View)	7
Figure 3-2	Typical Schematic.....	9
Figure 5-1	Package Dimensions PG-VQFN-32-13.....	14
Figure 5-2	Tape & Reel Dimensions PG-VQFN-32-13.....	14
Figure 5-3	Recommended Footprint PG-VQFN-32-13	14
Figure 5-4	Chip Marking PG-VQFN-32-13.....	15



List of Tables

List of Tables

Table 2-1	Device Configuration	6
Table 3-1	Buffer Types	7
Table 3-2	I/O Signals	7
Table 3-3	Power Supply	8
Table 3-4	Not Connected	8
Table 4-1	Absolute Maximum Ratings	10
Table 4-2	Functional Operating Range	10
Table 4-3	Current Consumption	11
Table 4-4	DC Characteristics of SPI Interface Pins (SCLK, CS#, MISO, MOSI, RST#, PIRQ#)	11
Table 4-5	DC Characteristics of GPIO and PP Pins	12
Table 4-6	Device Reset	12
Table 4-7	AC Characteristics of SPI Interface	12

1 Overview

The SLB 9670 is a Trusted Platform Module and is based on advanced hardware security technology. This TPM implementation has achieved CC EAL4+ certification and serves as a basis for other TPM products and firmware upgrades. It is available in PG-VQFN-32-13 package. It supports an SPI interface with a transfer rate of up to 43 MHz. The SLB 9670 is a TPM based on TCG family 2.0 specifications (see [\[1\]](#) and [\[2\]](#)).

- Compliant to TPM Main Specification, Family "2.0", Level 00, Revision 01.16
- SPI interface
- Meeting Intel TXT, Microsoft Windows and Google Chromebook certification criteria for successful platform qualification
- True Random Number Generator (TRNG)
- Full personalization with Endorsement Key (EK) and EK certificate
- Standard (-20..+85°C) and Enhanced temperature range (-40..+85°C)
- PG-VQFN-32-13 package
- Pin compatible to SLB 9670 TPM1.2 version
- Optimized for battery operated devices: low standby power consumption (typ. 110µA)
- 24 PCRs (SHA-1 or SHA-256)
- 7206 Byte free NV memory
- Up to 3 loaded sessions (TPM_PT_HR_LOADED_MIN)
- Up to 64 active sessions (TPM_PT_ACTIVE_SESSIONS_MAX)
- Up to 3 loaded transient Objects (TPM_PT_HR_TRANSIENT_MIN)
- Up to 7 loaded persistent Objects (TPM_PT_HR_PERSISTENT_MIN)
- Up to 8 NV counters
- Up to 1 kByte for command parameters and response parameters
- Up to 768 Byte for NV read or NV write
- 1280 Byte I/O buffer
- Built-in support by Linux Kernel

1.1 Power Management

In the SLB 9670, power management is handled internally; no explicit power-down or standby mode is available. The device automatically enters a low-power state after each successful command/response transaction. If a transaction is started on the SPI bus from the host platform, the device will wake immediately and will return to the low-power mode after the transaction has been finished.

2 Device Types / Ordering Information

The SLB 9670 product family features devices using a VQFN package. [Table 2-1](#) shows the different versions.

Table 2-1 Device Configuration

Device Name	Package	Remarks
SLB 9670VQ2.0	PG-VQFN-32-13	Standard temperature range
SLB 9670XQ2.0	PG-VQFN-32-13	Enhanced temperature range

Pin Description

3 Pin Description

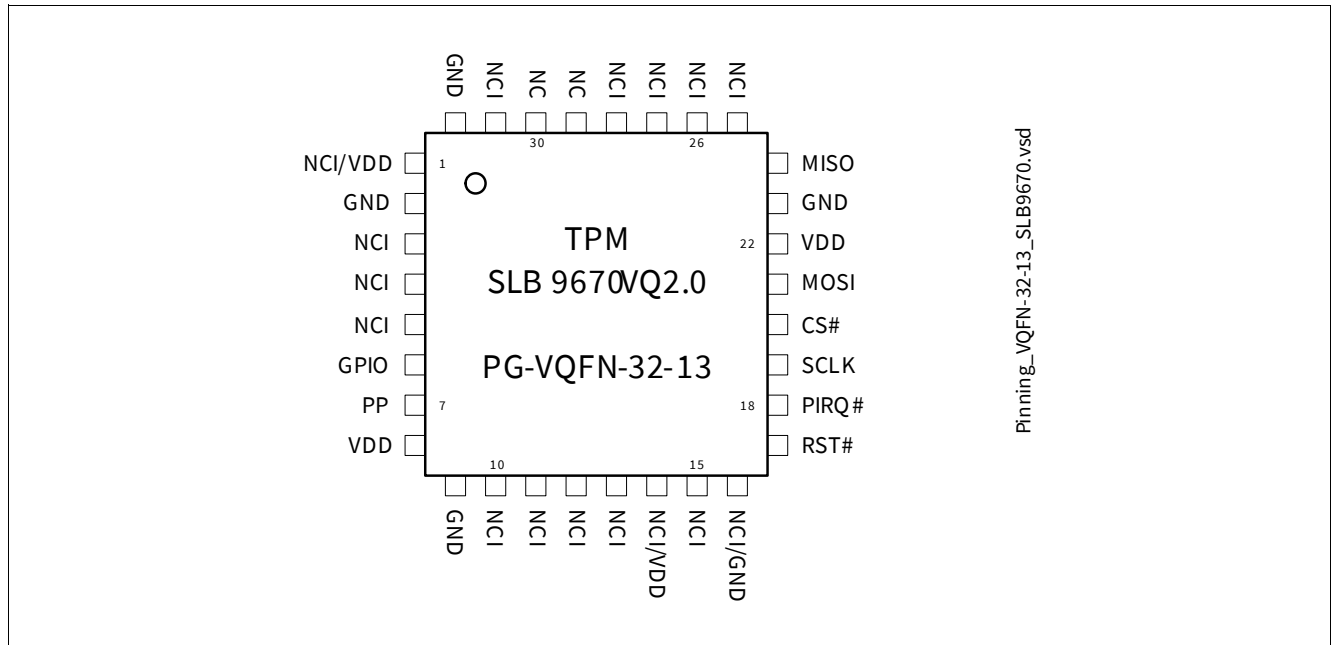


Figure 3-1 Pinout of the SLB 9670VQ2.0 (PG-VQFN-32-13 Package, Top View)

Table 3-1 Buffer Types

Buffer Type	Description
TS	Tri-State pin
ST	Schmitt-Trigger pin
OD	Open-Drain pin

Table 3-2 I/O Signals

Pin Number	Name	Pin Type	Buffer Type	Function
PG-VQFN-32-13				
20	CS#	I	ST	Chip Select The SPI chip select signal (active low).
19	SCLK	I	ST	SPI Clock The SPI clock signal. Only SPI mode 0 is supported by the device.
21	MOSI	I	ST	Master Out Slave In (SPI Data) SPI data which is received from the master.
24	MISO	O	TS	Master In Slave Out (SPI Data) SPI data which is sent to the SPI bus master.
18	PIRQ#	O	OD	Interrupt Request Interrupt request signal to the host. The pin has no internal pull-up resistor. The interrupt is active low.

Pin Description

Table 3-2 I/O Signals (continued)

Pin Number PG-VQFN-32-13	Name	Pin Type	Buffer Type	Function
17	RST#	I	ST	Reset External reset signal. Asserting this pin unconditionally resets the device. The signal is active low and is typically connected to the PCIRST# signal of the host. This pin has a weak internal pull-up resistor.
6	GPIO	I/O	TS	GPIO-Express-00 Signal See TCG specifications. This pin may be left unconnected; it has an internal pull-up resistor.
7	PP	I	ST	Physical Presence This pin indicates physical presence; for use, please refer to the TCG specification v1.2. The TPM2.0 device does not use this functionality; however, to minimize power consumption, this pin shall be connected to a fixed level (either GND or VDD). This pin may be left unconnected; it has an internal pull-down resistor.

Table 3-3 Power Supply

Pin Number PG-VQFN-32-13	Name	Pin Type	Buffer Type	Function
8, 22	VDD	PWR	—	Power Supply All VDD pins must be connected externally and should be bypassed to GND via 100 nF capacitors.
2, 9, 23, 32	GND	GND	—	Ground All GND pins must be connected externally.

Table 3-4 Not Connected

Pin Number PG-VQFN-32-13	Name	Pin Type	Buffer Type	Function
29, 30	NC	NU	—	No Connect All pins must not be connected externally (must be left floating).
3 - 5, 10 - 13, 15, 25 - 28, 31	NCI	—	—	Not Connected Internally All pins are not connected internally (can be connected externally).

Pin Description

Table 3-4 Not Connected (continued)

Pin Number	Name	Pin Type	Buffer Type	Function
PG-VQFN-32-13				
1, 14	NCI/VDD	—	—	Not Connected Internally/VDD All pins are not connected internally (can be connected externally). Note that pins 1 and 14 are defined as VDD in the TCG specification [2]. To be compliant, VDD can be connected to these pins.
16	NCI/GND	—	—	Not Connected Internally/GND This pin is not connected internally (can be connected externally). Note that pin 16 is defined as GND in the TCG specification [2]. To be compliant, GND can be connected to this pins.

3.1 Typical Schematic

Figure 3-2 shows the typical schematic for the SLB 9670. The power supply pins should be bypassed to GND with capacitors located close to the device.

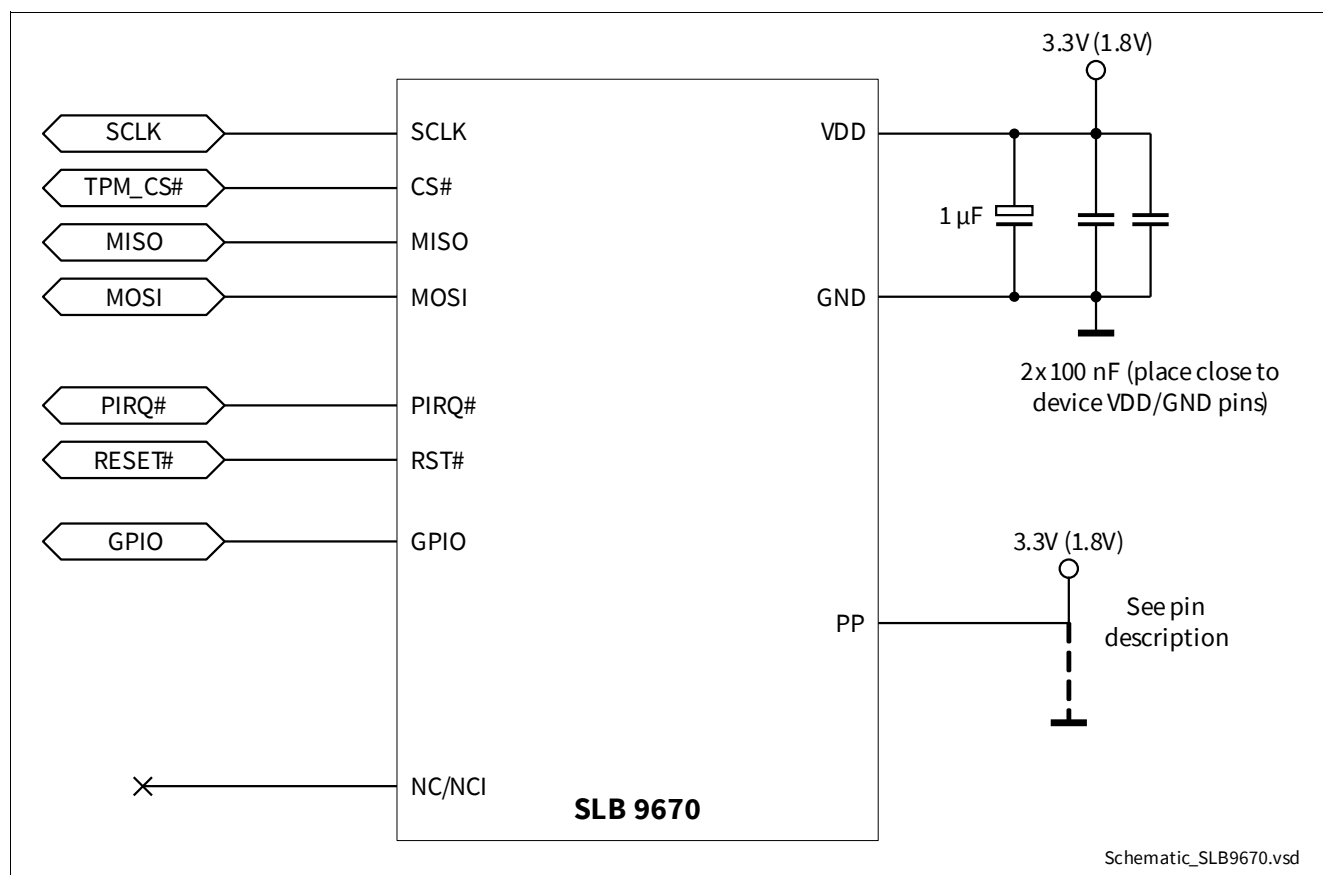


Figure 3-2 Typical Schematic

Electrical Characteristics

4 Electrical Characteristics

This chapter lists the maximum and operating ranges for various electrical and timing parameters.

4.1 Absolute Maximum Ratings

Table 4-1 Absolute Maximum Ratings

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Supply Voltage	V_{DD}	-0.3	–	7.0	V	–
Voltage on any pin	V_{max}	-0.3	–	$V_{DD}+0.3$	V	–
		-0.5	–	$V_{DD}+0.5$	V	$V_{DD} = 3.3V \pm 10\%$; pins MISO, MOSI, SCLK and CS#
Ambient temperature	T_A	-20	–	85	°C	Standard temperature devices
Ambient temperature	T_A	-40	–	85	°C	Enhanced temperature devices
Storage temperature	T_S	-40	–	125	°C	–
ESD robustness HBM: 1.5 k Ω , 100 pF	$V_{ESD,HBM}$	–	–	2000	V	According to EIA/JESD22-A114-B
ESD robustness	$V_{ESD,CDM}$	–	–	500	V	According to ESD Association Standard STM5.3.1 - 1999
Latchup immunity	I_{latch}			100	mA	According to EIA/JESD78

Attention: Stresses above the max. values listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Maximum ratings are absolute ratings; exceeding only one of these values may cause irreversible damage to the integrated circuit.

4.2 Functional Operating Range

Table 4-2 Functional Operating Range

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Supply Voltage	V_{DD}	3.0	3.3	3.6	V	–
		1.65	1.8	1.95	V	–
Ambient temperature	T_A	-20	–	85	°C	Standard temperature devices
Ambient temperature	T_A	-40	–	85	°C	Enhanced temperature devices
Useful lifetime ¹⁾		–	–	5	y	
Operating lifetime ¹⁾		–	–	5	y	
Average T_A over lifetime		–	55	–	°C	

1) The useful lifetime of the device is 5 (five) years with a duty cycle (that means, a power-on time) of 100%. A useful lifetime of 7 (seven) years can be guaranteed for a duty cycle of 70%. For both scenarios, it is assumed that the device will be used for calculations for approximately 5% of the maximum useful lifetime.

Electrical Characteristics

4.3 DC Characteristics

$T_A = 25^\circ\text{C}$, $V_{DD} = 3.3\text{V} \pm 0.3\text{V}$ or $V_{DD} = 1.8\text{V} \pm 0.15\text{V}$ unless otherwise noted.

Table 4-3 Current Consumption

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Current Consumption in Active Mode	I_{VDD_Active}			25	mA	
Current Consumption in Sleep Mode	I_{VDD_Sleep}		110		μA	Pin PP = GND, pins GPIO, RST# and PIRQ# = V_{DD} , CS# inactive (= V_{DD}), MOSI, MISO and SCLK don't care

Note: Current consumption does not include any currents flowing through resistive loads on output pins!

Table 4-4 DC Characteristics of SPI Interface Pins (SCLK, CS#, MISO, MOSI, RST#, PIRQ#)

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Input voltage high	V_{IH}	$0.7 V_{DD}$		$V_{DD}+0.5$	V	$V_{DD,typ} = 3.3\text{V}$, only pins SCLK, MISO, MOSI and CS#
		$0.7 V_{DD}$		$V_{DD}+0.3$	V	$V_{DD,typ} = 3.3\text{V}$, pin RST#
		$0.7 V_{DD}$		$V_{DD}+0.3$	V	$V_{DD,typ} = 1.8\text{V}$
Input voltage low	V_{IL}	-0.5		$0.3 V_{DD}$	V	$V_{DD,typ} = 3.3\text{V}$, only pins SCLK, MISO, MOSI and CS#
		-0.3		$0.3 V_{DD}$	V	$V_{DD,typ} = 3.3\text{V}$, pin RST#
		-0.3		$0.3 V_{DD}$	V	$V_{DD,typ} = 1.8\text{V}$
Input leakage current	I_{LEAK}	-20		20	μA	$0\text{V} < V_{IN} < V_{DD}$
		-150		150	μA	Pins SCLK, CS#, MISO, MOSI $-0.5\text{V} < V_{IN} < V_{DD}+0.5\text{V}$ $V_{DD,typ} = 3.3\text{V}$
		-150		150	μA	Pin RST# $-0.5\text{V} < V_{IN} < V_{DD}+0.3\text{V}$ $V_{DD,typ} = 3.3\text{V}$
		-150		150	μA	$-0.3\text{V} < V_{IN} < V_{DD}+0.3\text{V}$ $V_{DD,typ} = 1.8\text{V}$
Output high voltage	V_{OH}	$0.9 V_{DD}$			V	$I_{OH} = -100\mu\text{A}$
Output low voltage	V_{OL}			$0.1 V_{DD}$	V	$I_{OL} = 1.5\text{mA}$
Pad input capacitance	C_{IN}			10	pF	
Output load capacitance	C_{LOAD}			40	pF	

Electrical Characteristics

Table 4-5 DC Characteristics of GPIO and PP Pins

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Input voltage high	V_{IH}	$0.7 V_{DD}$		$V_{DD}+0.3$	V	Pins GPIO and PP
Input voltage low	V_{IL}	-0.3		$0.2 V_{DD}$	V	Pins GPIO and PP
Input leakage current	I_{LEAK}	-20		20	μA	$0V < V_{IN} < V_{DD}$
		-150		150	μA	$-0.3V < V_{IN} < V_{DD} + 0.3V$
Output high voltage	V_{OH}	$0.7 V_{DD}$			V	$I_{OH} = -1mA$, pin GPIO
Output low voltage	V_{OL}			0.3	V	$I_{OL} < 1mA$, pin GPIO
Pad input capacitance	C_{IN}			10	pF	Pins GPIO and PP

4.4 AC Characteristics

$T_A = 25^\circ C$, $V_{DD} = 3.3V \pm 0.3V$ or $V_{DD} = 1.8V \pm 0.15V$ unless otherwise noted.

Table 4-6 Device Reset

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
Reset Pulse Width	t_{RST}	80			μs	Cold (power-on) reset
Reset Pulse Width	t_{RST}	2			μs	Warm reset

Table 4-7 AC Characteristics of SPI Interface

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
SCLK frequency	f_{CLK}			43	MHz	$V_{DD,typ} = 3.3V$
				22.5	MHz	$V_{DD,typ} = 1.8V$
SCLK period	t_{CLK}	$1/f_{CLK} - 5\%$	$1/f_{CLK}$	$1/f_{CLK} + 5\%$	μs	Rising edge to rising edge, measured at $V_{IN} = 0.5 V_{DD}$
SCLK low time	t_{CLKL}	$0.45 t_{CLK}$			μs	Falling edge to rising edge, measured at $V_{IN} = 0.5 V_{DD}$
SCLK high time	t_{CLKL}	$0.45 t_{CLK}$			μs	Rising edge to falling edge, measured at $V_{IN} = 0.5 V_{DD}$
SCLK slew rate (rising/falling)	t_{SLEW}	1		4	V/ns	between $0.2 V_{DD}$ and $0.6 V_{DD}$
CS# high time	t_{CS}	50			ns	Rising edge to falling edge
CS# setup time	t_{CSS}	5			ns	CS# falling edge to SCLK rising edge
CS# hold time	t_{CSH}	5			ns	SCLK falling edge to CS# rising edge

Electrical Characteristics

Table 4-7 AC Characteristics of SPI Interface (continued)

Parameter	Symbol	Values			Unit	Note or Test Condition
		Min.	Typ.	Max.		
MOSI setup time	t_{SU}	2			ns	Data setup time to SCLK rising edge
MOSI hold time	t_H	3			ns	Data hold time from SCLK rising edge
MISO hold time	t_{HO}	0			ns	Output hold time from SCLK falling edge
MISO valid delay time	t_V	0		$0.7 t_{CLKL}$	ns	Output valid delay from SCLK falling edge

4.5 Timing

Some pads are disabled after deassertion of the reset signal for up to 500 μ s.

5 Package Dimensions (VQFN)

[illegible]

5.1 Packing Type

Technical drawing of the PG-VQFN-32-13-TP V01 package. The drawing shows a top view and a side view. The top view is a rectangle with dimensions 12 mm by 8 mm. It features a central square area with a side length of 5.25 mm, containing a crosshair pattern. The distance from the center of the package to the center of the crosshair is 5.25 mm. The side view shows a package with a thickness of 0.3 mm and a mounting pad width of 1.1 mm. A label 'Index Marking' points to a specific location on the top view.

PG-VQFN-32-13-TP V01

5.2 Recommended Footprint

PG-VQFN-32-13-FP V01

Data Sheet

Package Dimensions (VQFN)

5.3 Chip Marking

Line 1: SLB9670

Line 2: VQ20 yy or XQ20 yy (see [Table 2-1](#)), the <yy> is an internal FW indication (only at manufacturing due to field upgrade option)

Line 3: <Lot number> H <datecode>

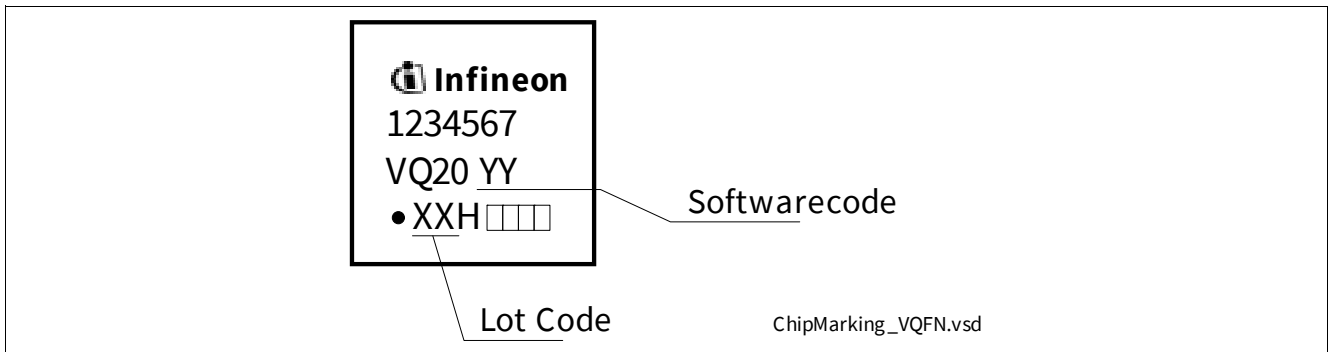


Figure 5-4 Chip Marking PG-VQFN-32-13

For details and recommendations regarding assembly of packages on PCBs, please refer to <http://www.infineon.com/cms/en/product/technology/packages/>

References

References

- [1] —, “Trusted Platform Module Library (Part 1-4)”, Family 2.0, Level 00, Rev. 01.16, 2014-10-30, TCG
- [2] —, “TCG PC Client Platform TPM Profile (PTP) Specification”, Family 2.0, Level 00, Rev. 43, January 26, 2015, TCG

Terminology

Terminology

ESW	Embedded Software
HMAC	Hashed Message Authentication Code
PCR	Platform Configuration Register
PUBEK	Public Endorsement Key
SPI	Serial Peripheral Interface (bus)
TCG	Trusted Computing Group
TPM	Trusted Platform Module
TSS	TCG Software Stack

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